# IR2170(S)

# **OVER CURRENT SENSING IC**

#### **Features**

- Floating channel up to +600V
- Monolithic integration
- Overcurrent sensing through shunt resistor
- Low IQBS allows the boot strap power supply
- Independent fast 1µsec overcurrent trip signal
- · High common mode noise immunity
- Input overvoltage protection for IGBT short circuit condition
- Open Drain outputs

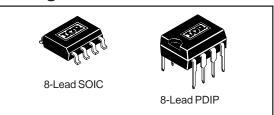
#### **Description**

IR2170(S) is the monolithic over current sensing IC designed for motor drive applications. It senses the motor phase current through an external shunt resistor, detects overcurrent condition, and transfers the signal to the low side. IR's proprietary high voltage isolation technology is implemented to enable the high bandwidth signal processing. The dedicated overcurrent trip  $(\overline{OC})$  signal facilitates IGBT short circuit protection. The  $\overline{OC}$ 

### **Product Summary**

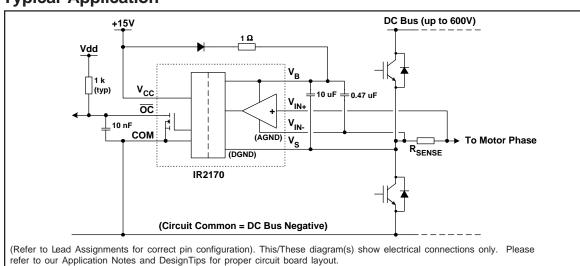
Voffset	600Vmax
I <sub>QBS</sub>	1mA
Overcurrent trip signal delay	1.5usec (typ)
Overcurrent trip level	+/-260mV (typ.)

## **Packages**



output pulse width can be programmed by the external resistor and capacitor. The open-drain outputs make easy for any interface from 3.3V to 15V.

# **Typical Application**



#### **Absolute Maximum Ratings**

Absolute maximum ratings indicate sustained limits beyond which damage to the device may occur. All voltage parameters are absolute voltages referenced to COM, all currents are defined positive into any lead. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions.

Symbol	Definition		Min.	Max.	Units
Vs	High side offset voltage		-0.3	600	
V <sub>BS</sub>	High side floating supply voltage		-0.3	25	
Vcc	Low side and logic fixed supply voltage		-0.3	25	
V <sub>IN</sub>	Maximum input voltage between V <sub>IN+ and</sub> V <sub>IN-</sub>		-5	5	V
Voc	Overcurrent output voltage		COM -0.3	VCC +0.3	
V <sub>IN-</sub>	V <sub>IN-</sub> input voltage (note 1)		V <sub>S</sub> -5	V <sub>B+</sub> 0.3	
dV/dt	Allowable offset voltage slew rate		_	50	V/ns
PD	Package power dissipation @ T <sub>A</sub> ≤ +25°C	8 lead SOIC	_	.625	
		8 lead PDIP	_	1.0	W
RthJA	Thermal resistance, junction to ambient	8 lead SOIC	_	200	0000
		8 lead PDIP	_	125	°C/W
TJ	Junction temperature		_	150	
T <sub>S</sub>	Storage temperature		-55	150	°C
TL	Lead temperature (soldering, 10 seconds)		_	300	

Note 1: Capacitors are required between VB and Vin-, and between VB and Vs pins when bootstrap power is used. The external power supply, when used, is required between Vs and Vin-, and between VB and Vs pins.

## **Recommended Operating Conditions**

The output logic timing diagram is shown in figure 1. For proper operation the device should be used within the recommended conditions.

Symbol	Definition	Min.	Max.	Units
V <sub>B</sub>	High side floating supply voltage	V <sub>S</sub> +13.0	V <sub>S</sub> +20	
Vs	High side floating supply offset voltage	note 2	600	
Voc	Overcurrent output voltage	COM	VCC	V
Vcc	Low side and logic fixed supply voltage	9.5	20	
VIN	Input voltage between V <sub>IN+</sub> and V <sub>IN-</sub>	-260	+260	mV
T <sub>A</sub>	Ambient temperature	-40	125	°C

Note 2: Logic operation for Vs of -5 to +600V. Logic state held for Vs of -5V to -VBs. (Please refer to the Design Tip DT97-3 for more details).

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#### **DC Electrical Characteristics**

 $V_{CC} = V_{BS} = 15V$ , and  $T_A = 25^{\circ}C$  unless otherwise specified.

Symbol	Definition	Min.	Тур.	Max.	Units	<b>Test Conditions</b>
V <sub>OC+</sub>	Overcurrent trip positive input voltage	_	260		>/	
V <sub>OC</sub> -	Overcurrent trip negative input voltage	_	-260	_	mV	
I <sub>LK</sub>	Offset supply leakage current	_	_	50	μΑ	V <sub>B</sub> = V <sub>S</sub> = 600V
I <sub>QBS</sub>	Quiescent V <sub>BS</sub> supply current	_	1	2		V <sub>S</sub> = 0V
IQCC	Quiescent V <sub>CC</sub> supply current	_	_	0.5		
locc	OC output sink current	10	_		mA	V <sub>O</sub> = 1V
		1	_	_		V <sub>O</sub> = 0.1V

### **AC Electrical Characteristics**

 $V_{CC} = V_{BS} = 15V$ , and  $T_A = 25^{\circ}C$  unless otherwise specified.

Symbol	Definition	Min.	Тур.	Max.	Units	Test Conditions
Proagatio	n delay characteristics					
tdoc	Propagation delay time of OC	1	1.5	_	usec	
twoc	Low true pulse width of OC	_	1	_		

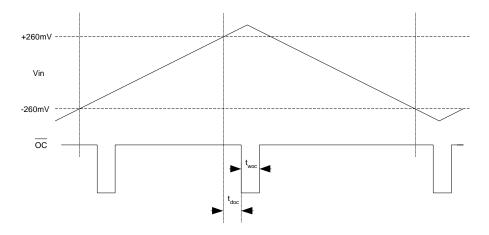


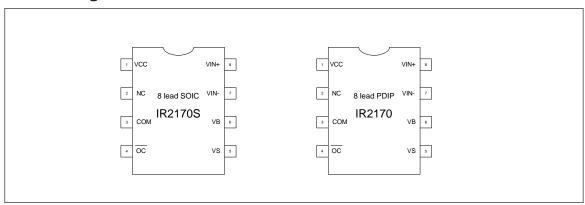
Figure 1. OC Waveform

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# **Lead Definitions**

Symbol	Description
Vcc	Low side and logic supply voltage
COM	Low side logic ground
V <sub>IN+</sub>	Positive sense input
VIN-	Negative sense input
VB	High side supply
Vs	High side return
<u>oc</u>	Overcurrent output (negative logic)
N.C.	No connection

# **Lead Assignments**



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#### Case outlines

